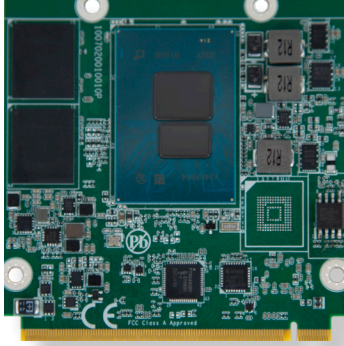


EmQ-iX702



Intel® Amston Lake Qseven R2.1 CPU Module



Features

- Soldered onboard Intel Amston lake SoC Processor
- Soldered onboard LPDDR5 4GB/8GB/16GB SDRAM
- Integrated 1 Gigabit Ethernet Controller
- Dual Channel 24-bit LVDS and 1 x DDI port
- Compliant with Qseven specifications revision 2.1

System

CPU	Soldered onboard Intel® Atom® x7211RE 1.0GHz/3.2GHz(Turbo) Dual cores TDP 6W Atom® x7433RE 1.5GHz/3.5GHz(Turbo) Quad cores TDP 9W
Memory	Soldered onboard LPDDR5 4800MT/s 4GB / 8GB / 16GB
BIOS	AMI UEFI BIOS
TPM	Support TPM 2.0

I/O

USB Port	6 x USB 2.0 ports 2 x USB 3.2 ports
Serial Port	1 x UART
Expansion Bus	4 x PCIe1 Gen3 lanes, I ² C, SMBus, SPI
Storage	2 x SATA 3.0 ports Soldered onboard eMMC 5.1 (OEM Request)
Ethernet Chipset	1 x Intel® i210 Ethernet controller
Audio	HD link

Display

Graphic Chipset	Integrated in Intel® Gen12 graphic Dual Channel 24-bit LVDS, with resolution up to 1920x1200
Graphic Interface	1 x DDI port supports HDMI 2.0b or DP1.4 or eDP1.4b with resolution up to 4096x2304@60HZ

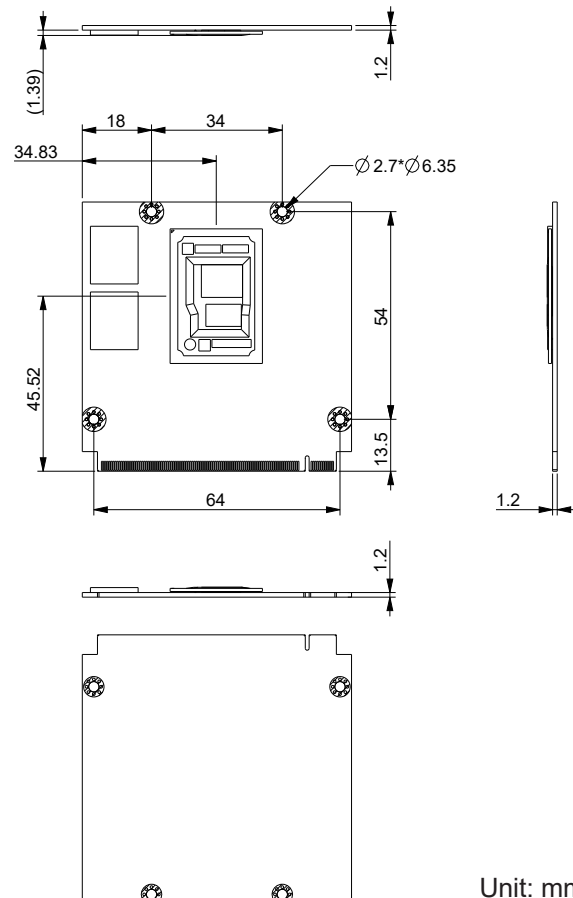
OS support

Windows 10/11 64-bit
Linux: Ubuntu

Mechanical & Environmental

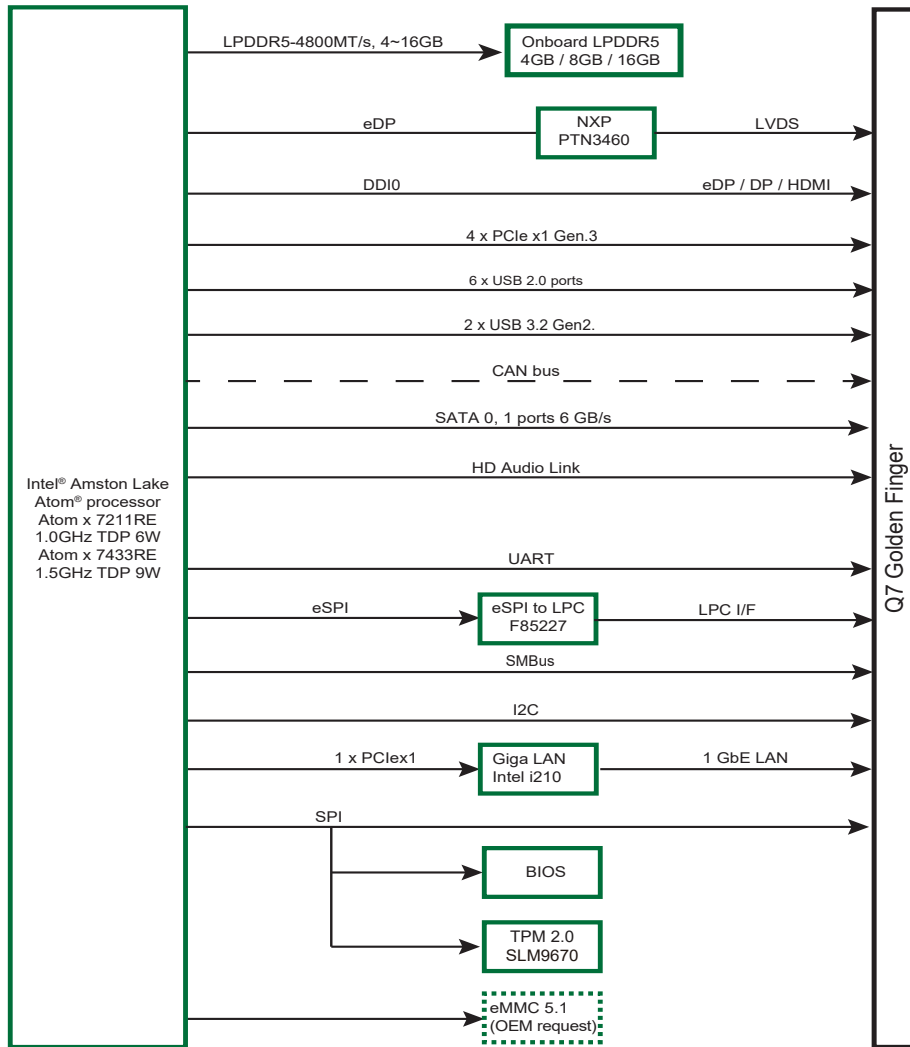
Power Requirement	DC 5V, 5VSB
Operating Temp.	-40 ~ 85°C (-40~185°F)
Operating Humidity	10 ~ 95% @ 85°C (non-condensing)
Dimensions (L x W)	70 x 70 mm (2.76" x 2.76")

Dimension



Unit: mm

Block Diagram



Ordering Information

EmQ-iX702-WT-x7211RE-4G Qseven R2.1 Intel® Amston Lake ATOM x7211RE CPU Module w/4G memory down, -40~85°C

EmQ-iX702-WT-x7433RE-8G Qseven R2.1 Intel® Amston Lake ATOM x7433RE CPU Module w/8G memory down, -40~85°C

Optional Accessories

HS-X702-F1 Heat spreader

PBQ-900R Qseven R2.1 ATX form factor carrier board (All Super IO port functions are OEM requested)

CBK-02-900R-00 Cable Kit